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PATENT

Docket No. JCLA6353

Date: 5-23-2001

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ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231
ATTENTION: APPLICATION BRANCH

Sir:

Transmitted herewith for filing is the patent application of

Inventors: Chingfu Lin; Hsueh-Chung Chen

For: A DUAL DAMASCENE PARTIAL GAP FILL POLYMER FABRICATION PROCESS

Enclosed are:

- Specification 13 pages.
- 5 Sheets of drawings
- Recordation Form Cover sheet with 2 pages assignment.
- A certified copy of Taiwan Patent Application No. dated .
- SIGNED declaration and power of attorney.
- Return Prepaid postcard.

CLAIMS AS FILED

FOR	NUMBER FILED	NUMBER EXTRA	RATE	FEE
Basic Fee			\$710.00	\$710.00
Total Claims	16	— 20 = 0 ×	\$18.00	\$0.00
Independent Claims	1	— 3 = 0 ×	\$80.00	\$0.00
If application contains any multiple dependent claim(s), then add			\$270.00	\$0.00
TOTAL FILING FEE				\$710.00

- A check in the amount of \$710.00 cover the filing fee is enclosed.
- A check in the amount of \$40.00 to cover the assignment recording fee.
- A duplicate copy of this sheet is enclosed.

Jiawei Huang

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CERTIFICATE OF MAILING BY "EXPRESS MAIL"

Docket No. : JCLA6353
Applicant(s) : Chingfu Lin; Hsueh-Chung Chen
For : A DUAL DAMASCENE PARTIAL GAP FILL POLYMER
FABRICATION PROCESS
"Express Mail" : EL800897094US
Mailing Label No.
Date of Deposit : May 23, 2001

I hereby certify that the accompanying

Transmittal in Duplicate; Specification 13 pages, 5 sheets of drawings; SIGNED
Declaration and Power of Attorney 2 pages; Recordation Form Cover Sheet and
Assignment 3 pages; Checks for Filing Fee(s); Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to
Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the
Assistant Commissioner for Patents, Washington, D.C. 20231.

M. Chang
Michelle Chang